

U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified)					Docket No. AMAT/3786.Y1/CMP/ CMP/RKK		Serial No. 09/469,709	
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT					Applicant Li, et al.		Confirmation No. 5296	
(Use several sheets if necessary)					Filing Date December 21, 1999		Group 1763	
Examiner George A. Goudreau								
U.S. Patent Documents								
*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate	
gag	A1	6,001,730 ✓	12/14/1999	Farkas, et al.	438	627	10/20/1997	
	A2	5,994,224 ✓	11/30/1999	Sandhu, et al.	438	692	12/17/1997	
	A3	5,738,574 ✓	04/14/1998	Tolles, et al.	451	288	10/27/1995	
	A4	5,516,346 ✓	05/14/1996	Cadien, et al.	51	308	05/13/1994	
Foreign Patent Documents								
*Examiner Initial		Document Number	Date	Country	Class	Subclass	Translation	
gag	B1	1 085 067 ✓	11/31/1999	EP	G09G	1/02	YES	NO
	B2	1 093 161 ✓	10/11/2000	EP	H01L	24/568	YES	NO
	B3	1 057 591 ✓	12/06/2000	EP	B24B	3/204	YES	NO
	B4	00/35627 ✓	06/22/2000	WO	B24B	3/204	YES	NO
	B5	98/49723 ✓	11/05/1998	WO	H01L	24/521	YES	NO
	B6	00/30154 ✓	05/24/2000	WO	H01L	3/204	YES	NO
	B7	00/59031 ✓	10/05/2000	WO	H01L	24/568	YES	NO
	B8	00/25984 ✓	05/11/2000	WO	B24B	3/204	YES	NO
OTHER ART								
*Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.						
gag	C1	European Search Report for 00311569.8 dated November 12, 2003 (AMAT/3786.EP) ✓						
	C2	Peterson, et al., "Investigating CMP and Post-CMP Cleaning Issues for Dual-Damascene Copper Technology" Micro Computerist, Volume 17 No. 1 January 1999 Pages 27-32, 34. ✓						
	C3	Hayashi, et al. "A New Two-Step Metal-CMP Technique for a High Performance Multilevel Interconnects Featured by Al-AND CU in Low Epsilon, Organic Film-Metallizations" 1996 Symposium on VLSI Technology, Digest of Technical Papers Pages 88-89. ✓						
	C4	Schraub, et al., "Chemical Mechanical Polishing: Future Processing Require CMP Tool Flexibility" Proceedings of the SPIE, Volume 3508 September 1998 Pages 146-154 ✓						
	C5	Wijekoon, et al. "Development of a Production Worthy Copper CMP Process" Advanced Semiconductor Manufacturing Conference and Workshop, September 1998, Pages 354-363. ✓						
Examiner George Goudreau					Date Considered 3-04/			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.								